# 2SC3312

## Silicon NPN epitaxial planar type

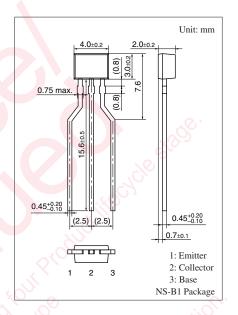
For low-frequency and low-noise amplification Complementary to 2SA1310

#### ■ Features

- Optimum for high-density mounting
- Allowing supply with the radial taping
- Low noise voltage NV

### ■ Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	$V_{CBO}$	60	V	
Collector-emitter voltage (Base open)	$V_{CEO}$	55	V	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	7	V	
Collector current	$I_{C}$	100	mA	
Peak collector current	$I_{CP}$	200	mA	
Collector power dissipation	P <sub>C</sub>	300	mW	
Junction temperature	$T_{j}$	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°CO	



### ■ Electrical Characteristics T<sub>a</sub> = 25°C ± 3°C

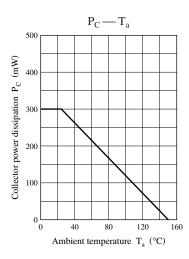
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 10 \mu\text{A}, I_E = 0$	60	0.		V
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = 2 \text{ mA}, I_B = 0$	55			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \mu\text{A}, I_C = 0$	7			V
Base-emitter voltage	V <sub>BE</sub>	$V_{CE} = 1 \text{ V}, I_{C} = 30 \text{ mA}$			1	V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 20 \text{ V}, I_E = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I <sub>CEO</sub>	$V_{CE} = 20 \text{ V}, I_{B} = 0$			1	μΑ
Forward current transfer ratio *	h <sub>FE</sub>	$V_{CE} = 5 \text{ V}, I_C = 2 \text{ mA}$	180		700	
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 100 \text{ mA}, I_B = 10 \text{ mA}$			1	V
Transition frequency	$f_T$	$V_{CB} = 5 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$ 200			MHz	
Noise voltage	NV	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ mA}, G_{V} = 80 \text{ dB}$			150	mV
		$R_g = 100 \text{ k}\Omega$ , Function = FLAT				

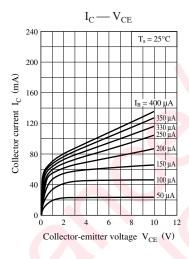
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

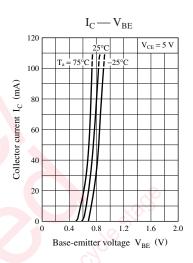
#### 2. \*: Rank classification

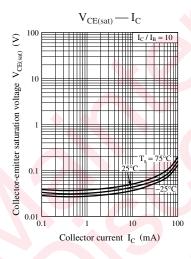
Rank	R	S	Т
$h_{FE}$	180 to 360	260 to 520	360 to 700

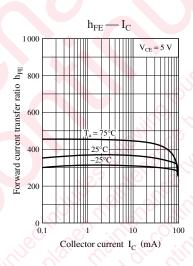
## **Panasonic**

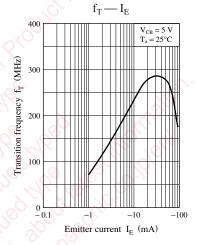


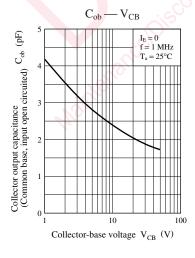


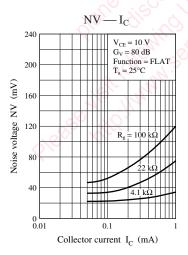












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